

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>KiYoun Jang</td> <td>04/21/2010</td> </tr> <tr> <td>Daesik Choi</td> <td>04/21/2010</td> </tr> <tr> <td>Ohhan Kim</td> <td>04/21/2010</td> </tr> <tr> <td>DongSoo Moon</td> <td>04/21/2010</td> </tr> </tbody> </table>		Name	Execution Date	KiYoun Jang	04/21/2010	Daesik Choi	04/21/2010	Ohhan Kim	04/21/2010	DongSoo Moon	04/21/2010
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KiYoun Jang	04/21/2010										
Daesik Choi	04/21/2010										
Ohhan Kim	04/21/2010										
DongSoo Moon	04/21/2010										
RECEIVING PARTY DATA											
Name:	STATS ChipPAC, Ltd.										
Street Address:	10 Ang Mo Kio Street 65										
Internal Address:	#05-17/20 Techpoint										
City:	Singapore										
State/Country:	SINGAPORE										
Postal Code:	569059										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12764805</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12764805						
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Application Number:	12764805										
CORRESPONDENCE DATA											
Fax Number:	(602)748-4414										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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Address Line 1:	605 W. Knox Road										
Address Line 2:	Suite 104										
Address Line 4:	Tempe, ARIZONA 85284										
ATTORNEY DOCKET NUMBER:	2515.0260										
NAME OF SUBMITTER:	Robert D. Atkins										

OP \$40.00 12764805

501154723

**PATENT
 REEL: 024267 FRAME: 0839**

Total Attachments: 4

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KIYOUN JANG of Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING BUMP ON SUBSTRATE TO PREVENT ELK ILD DELAMINATION DURING REFLOW PROCESS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0260, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



Signature for KIYOUN JANG

Witnessed on this date: 4.21'10

Signature of Witness: 

Printed Name of Witness: Lee Hyung Min

Address of Witness: Hobymun road, Gangdong, Gyeonggi, Korea

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, DAESIK CHOI of Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING BUMP ON SUBSTRATE TO PREVENT ELK ILD DELAMINATION DURING REFLOW PROCESS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0260, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for DAESIK CHOI

Witnessed on this date: 04.21.10

Signature of Witness: 

Printed Name of Witness: Lee Hyung Man

Address of Witness: Mokryun road, Gangdong, Gyeonggi, Korea

ASSIGNMENT AND AGREEMENT

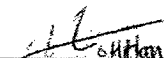
For good and valuable consideration, the receipt of which is hereby acknowledged, I, OHHAN KIM of Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING BUMP ON SUBSTRATE TO PREVENT ELK ILD DELAMINATION DURING REFLOW PROCESS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0260, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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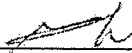
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Signature for OHHAN KIM

Witnessed on this date: 04.21'10

Signature of Witness: 

Printed Name of Witness: Lee Hyoung Min

Address of Witness: Mobryunmari, Songdo, Gyeonggi, Korea

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For good and valuable consideration, the receipt of which is hereby acknowledged, I, DONGSOO MOON of Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING BUMP ON SUBSTRATE TO PREVENT ELK ILD DELAMINATION DURING REFLOW PROCESS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0260, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for DONGSOO MOON

Witnessed on this date: 04.21'10

Signature of Witness: 

Printed Name of Witness: Lee Hwang Min

Address of Witness: Mobipin road, Gangdong, Gyeonggi, Korea
